



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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INTERCONNECTS

SERIES 304, 346 • .100" GRID SOLDERLESS PRESS-FIT • SINGLE ROW STRIPS

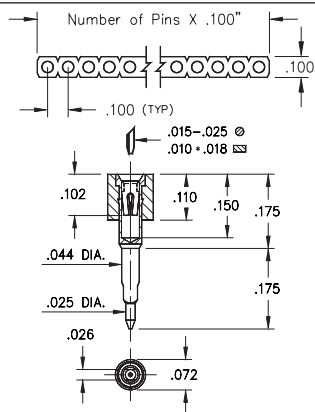


FIG. 1

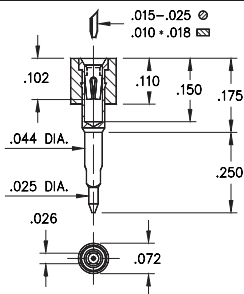


FIG. 2

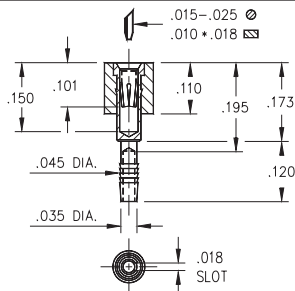


FIG. 3

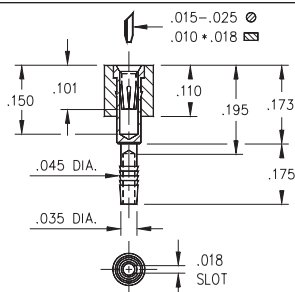


FIG. 4

- Unique compliant tail pins conform to the plated through-hole without stressing the inner layers of a multilayer board
- Recommended plated through-hole for 304 series: .036"-.041" use a 1,1mm drill prior to plating. Using MM #0477 & #0478 pins. See page 162 for details
- For 346 series: .040"±.003" finished plated through-hole. Using MM #4612 & #4613 pins. See page 162 for details. Patent No. 4,799,904
- Hi-Rel, 4-finger BeCu #30 contact is rated at 3 amps. See page 253 for details
- Insulators are high temperature thermoplastic



ORDERING INFORMATION

FIG. 1	Series 304...770 Solderless Press-Fit																											
	For .062" Thick Boards 304-XX-1__-41-770000 Specify number of pins ↑ 01-64																											
FIG. 2	Series 304...780 Solderless Press-Fit																											
	For .125" Thick Boards 304-XX-1__-41-780000 Specify number of pins ↑ 01-64																											
Mill-Max recommends plating Code 13 for Series 304...770 and 304...780																												
FIG. 3	Series 346...012 Compliant Solderless Press-Fit																											
	For .060"-.100" Thick Boards 346-XX-1__-41-012000 Specify number of pins ↑ 01-64																											
FIG. 4	Series 346...013 Compliant Solderless Press-Fit																											
	For .090"-.130" Thick Boards 346-XX-1__-41-013000 Specify number of pins ↑ 01-64																											
<div style="display: flex; justify-content: space-around; align-items: center;"> <div style="border: 1px solid black; padding: 5px; background-color: #90EE90;">RoHS-2 2011/65/EU</div> <div style="border: 1px solid black; border-radius: 50%; padding: 5px;">XX=Plating Code See Below</div> <div style="border: 1px solid black; border-radius: 50%; padding: 5px;">For Electrical, Mechanical & Environmental Data, See page 264</div> </div>																												
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: left;">SPECIFY PLATING CODE XX=</th> <th>11</th> <th>13</th> <th>91</th> <th>93</th> <th>99</th> <th>41</th> <th>43</th> <th>44</th> </tr> </thead> <tbody> <tr> <td>Sleeve (Pin) </td> <td>10 μ" Au</td> <td>10 μ" Au</td> <td>200 μ" Sn/Pb</td> <td>200 μ" Sn/Pb</td> <td>200 μ" Sn/Pb</td> <td>200 μ" Sn</td> <td>200 μ" Sn</td> <td>200 μ" Sn</td> </tr> <tr> <td>Contact (Clip) </td> <td>10 μ" Au</td> <td>30 μ" Au</td> <td>10 μ" Au</td> <td>30 μ" Au</td> <td>100 μ" Sn/Pb</td> <td>10 μ" Au</td> <td>30 μ" Au</td> <td>100 μ" Sn</td> </tr> </tbody> </table>		SPECIFY PLATING CODE XX=	11	13	91	93	99	41	43	44	Sleeve (Pin)	10 μ" Au	10 μ" Au	200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn	200 μ" Sn	200 μ" Sn	Contact (Clip)	10 μ" Au	30 μ" Au	10 μ" Au	30 μ" Au	100 μ" Sn/Pb	10 μ" Au	30 μ" Au	100 μ" Sn
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